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DATE MAILED: 02/08/2005

APPLICATION	NO. F	ILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
10/800,450		03/15/2004	Emmanuel Hadji	33019US1	1230
116	7590	02/08/2005		EXAMINER	
	E & GORD ST 9TH STR		LUU, CHUONG A		
SUITE 1				ART UNIT	PAPER NUMBER
CLEVELAND, OH 44114-3108				2818	

Please find below and/or attached an Office communication concerning this application or proceeding.

		AL	/
	Application No.	Applicant(s)	
	10/800,450	HADJI ET AL.	
Office Action Summary	Examiner	Art Unit	
	Chuong A. Luu	2818	
The MAILING DATE of this communication ap	ppears on the cover sheet wi	th the correspondence address	
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1. after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a rep  - If NO period for reply is specified above, the maximum statutory period  - Failure to reply within the set or extended period for reply will, by statut Any reply received by the Office later than three months after the mailine earned patent term adjustment. See 37 CFR 1.704(b).	.136(a). In no event, however, may a re oly within the statutory minimum of thirt I will apply and will expire SIX (6) MON te, cause the application to become AB.	eply be timely filed  (30) days will be considered timely.  THS from the mailing date of this communication.  ANDONED (35 U.S.C. § 133).	
Status			
Responsive to communication(s) filed on <u>26 J</u> This action is <b>FINAL</b> . 2b)⊠ Thi      Since this application is in condition for alloware closed in accordance with the practice under	s action is non-final. ance except for formal matte	•	•
Disposition of Claims			
4) ⊠ Claim(s) 1-15 is/are pending in the application 4a) Of the above claim(s) is/are withdra 5) □ Claim(s) is/are allowed. 6) ⊠ Claim(s) 1-15 is/are rejected. 7) □ Claim(s) is/are objected to. 8) □ Claim(s) are subject to restriction and/or	awn from consideration.		
Application Papers			
9) The specification is objected to by the Examina	er		
10) The drawing(s) filed on is/are: a) acceptable and any objection to the Replacement drawing sheet(s) including the correct and the oath or declaration is objected to by the E	cepted or b) objected to be drawing(s) be held in abeyand ction is required if the drawing(	ce. See 37 CFR 1.85(a). s) is objected to. See 37 CFR 1.121(d).	
Priority under 35 U.S.C. § 119			
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of:  1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority document application from the International Bureat * See the attached detailed Office action for a list.	its have been received. Its have been received in Apority documents have been Bu (PCT Rule 17.2(a)).	oplication No received in this National Stage	
Attachment(s)  1) ☑ Notice of References Cited (PTO-892)  2) ☑ Notice of Draftsperson's Patent Drawing Review (PTO-948)  3) ☑ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)	Paper No(s	ummary (PTO-413) //Mail Date formal Patent Application (PTO-152)	

U.S. Patent and Trademark Office PTOL-326 (Rev. 1-04)

Paper No(s)/Mail Date \_\_\_\_

6) Other: \_\_\_\_\_.

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#### **DETAILED ACTION**

## Response to Arguments

Applicant's arguments with respect to claims 1-15 have been considered but are most in view of the new ground(s) of rejection.

#### PRIOR ART REJECTION

#### **Statutory Basis**

# Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

#### The Rejections

Claims 1-2 and 4 are rejected under 35 U.S.C. 102(e) as being anticipated by Biasse et al (5,993,677).

As to claims 1-2, Biasse discloses a process, wherein molecular bonding of a silicon block (120) having a surface layer (124) delimited by a cleavage area (126) substantially parallel to its surface and the silicon block being covered by silicon oxide layer (112) brought into contact with a support layer (132) (see column 3, lines 14-17 and column 4, lines 38-54);

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Biasse teaches cleavage of the silicon block along the cleavage area to detach the surface layer fixed to the support (see column 4, lines 55-62. Figures 9-10);

Biasse teaches that an etching process is to eliminate or thinning the surface layer in order to have a desired thickness (see column 5, lines 9-11);

As to claim 2, Biasse inherently teaches that the thickness of the surface layer is greater than the desired thickness because after cleavage, an etching is performed for thinning to a desired thickness.

As to claim 4, Biasse teaches that the cleavage zone is formed using hydrogen implantation (see column 3, lines 18-23).

## **Statutory Basis**

# Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was

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not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

## The Rejections

Claim 3 is rejected under 35 U.S.C. 103(a) as being unpatentable over Biasse et al (5,993,677) in view of Ohmura et al (4,848,272).

Biasse discusses above in the paragraph 4 but fail to disclose to increase the thickness by crystalline growth. It would have been obvious to one skilled in the art to increase the thickness if the thickness is less than the predetermined thickness and furthermore, crystalline growth is conventional technique to form an epitaxial layer on a silicon substrate as supported by Ohmura. Ohmura teaches that crystalline growth is conventional to provide a high quality thin film having uniform thickness over a semiconductor substrate (see column 1, lines 10-14 and column 2, lines 3-7).

Claims 5-15 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ramdani et al (5,835,521) in view of Biasse et al (5,993,677).

Ramdani discloses a bragg mirror structure (10) including alternating layers of silicon oxide and a silicon material utilizing epitaxial growth technique and /or wafer bonding, wherein the alternating silicon oxide and silicon layers inherently includes the optical property such as the optical thickness of the alternating layers (see column 3, lines 17-25);

As to claim 6, Ramdani teaches that silicon oxide layer is formed by standard epitaxial growth technique including CVD or PECVD technique (see column 3, lines 18-25);

Ramdani also discloses that an optical component is formed by fabricating a vertical cavity surface emitting laser or active region on the bragg mirror (see column 3, lines 9-55);

Ramdani also teaches that a second mirror (42) is disposed over the active region (see column 6, lines 4-24);

Ramdani fails to teach the formation of silicon layer as the context of claim 1 namely bonding a silicon block with a support, cleaving the silicon block and thinning the surface layer to a desired thickness. However, Biasse discusses in the paragraph 4 above in order to efficiently form a silicon layer with a desired thickness. Therefore, it would have been obvious to one skilled in the art at the time of claimed invention to combine Biasse 's teaching into Ramdani 's process for easily providing a predetermined thickness of the silicon layer as taught by Biasse.

### Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Chuong A. Luu whose telephone number is (571) 272-1902. The examiner can normally be reached on M-F (6:15-2:45).

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If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, David C. Nelms can be reached on (571) 272-1787. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Chuong Anh Luu

Examiner

February 5, 2005